

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE BY SECURED PARTY
CONVEYING PARTY DATA	
Name	Execution Date
GOLDMAN SACHS LENDING PARTNERS LLC	11/29/2013
RECEIVING PARTY DATA	
Name:	ISOLA USA CORP.
Street Address:	3100 WEST RAY ROAD
Internal Address:	SUITE 301
City:	CHANDLER
State/Country:	ARIZONA
Postal Code:	85226
PROPERTY NUMBERS Total: 49	
Property Type	Number
Patent Number:	5098781
Patent Number:	5262491
Patent Number:	5160567
Patent Number:	5350621
Patent Number:	5334696
Patent Number:	5362534
Patent Number:	5387656
Patent Number:	5437914
Patent Number:	5457319
Patent Number:	5464658
Patent Number:	5508328
Patent Number:	5512381
Patent Number:	5545466
Patent Number:	5557843

Patent Number:	5626774
Patent Number:	5626804
Patent Number:	5670250
Patent Number:	5779870
Patent Number:	6083855
Patent Number:	6168898
Patent Number:	6187852
Patent Number:	6242078
Patent Number:	6255039
Patent Number:	6322885
Patent Number:	6403229
Patent Number:	6509414
Patent Number:	6584820
Patent Number:	6609294
Patent Number:	6618238
Patent Number:	6632511
Patent Number:	6658375
Patent Number:	6768316
Patent Number:	6955740
Patent Number:	7090924
Patent Number:	7255927
Patent Number:	7425371
Patent Number:	7507471
Patent Number:	7521494
Patent Number:	7687556
Patent Number:	7713621
Patent Number:	7897258
Patent Number:	7910202
Patent Number:	8022140
Patent Number:	8129456
Patent Number:	8227084
Patent Number:	8263225
Application Number:	11634471
Application Number:	10952102
Application Number:	12610004

PATENT

REEL: 031751 FRAME: 0829

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ATTORNEY DOCKET NUMBER:	049274-0009
NAME OF SUBMITTER:	ANGELA M. AMARU
Signature:	/s/ Angela M. Amaru
Date:	12/03/2013

Total Attachments: 5

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RELEASE OF SECURITY INTEREST IN PATENTS

This Release of Security Interest in Patents (this "Release") is made as of November 29, 2013 (the "Effective Date") by GOLDMAN SACHS LENDING PARTNERS LLC, in its capacity as Collateral Agent for the benefit of ISOLA USA Corp. (the "Company"). Unless otherwise defined herein, capitalized terms used herein shall have the meaning ascribed to them in the Patent Security Agreement (as defined below).

WHEREAS, pursuant to the terms and conditions of that certain Patent Security Agreement dated as of September 30, 2010 by and between the Company and the Collateral Agent (the "Patent Security Agreement"), the Company granted to the Collateral Agent for the benefit of the Secured Parties a security interest in and continuing lien on all of the Company's right, title and interest in, to and under the following, in each case whether then owned or thereafter existing or in which the Company then had or thereafter acquired an interest and wherever the same may be located, all United States patents and certificates of invention, or similar industrial property rights, and applications for any of the foregoing, including, without limitation: (i) each patent and patent application listed in Schedule A attached hereto, (ii) all reissues, divisions, continuations, continuations-in-part, extensions, renewals, and reexaminations thereof, (iii) all patentable inventions and improvements thereto, (iv) the right to sue or otherwise recover for any past, present and future infringement or violation or impairment thereof, (v) all Proceeds of the foregoing, including, without limitation, license fees, royalties, income, payments, claims, damages and proceeds of suit then or thereafter due and/or payable with respect thereto, and (vi) all other rights of any kind accruing thereunder or pertaining thereto throughout the world (collectively, the "Patent Collateral"); and

WHEREAS, the Patent Security Agreement was executed by the Company and was previously recorded in the United States Patent and Trademark Office ("USPTO") on October 1, 2010 at Patent Reel No. 025077, Frame No. 0427; and

WHEREAS, the Collateral Agent has agreed to release its security interest in all of the right, title, and interest of the Company in the Patent Collateral, and to reconvey any and all right, title, or interest it may have in the Patent Collateral to the Company; and

NOW, THEREFORE, in consideration of the foregoing, and for other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, Collateral Agent hereby releases, relinquishes and discharges, all of its security interest in and continuing lien on all of the Company's right, title and interest in, to and under the Patent Collateral, and re-assigns to the Company any and all right, title or interest it may have in such Patent Collateral, all without warranty and representation of any kind.

The Collateral Agent hereby authorizes the Company, or the Company's authorized representatives to: (a) record this Release with the USPTO and/or any other applicable governmental office or Agency, and (b) file UCC financing statement amendments with the applicable filing office in order to memorialize the release of the security interest of the Collateral Agent in the Patent Collateral. The Collateral Agent agrees to execute and deliver to the Company all other instruments and other documents as may be necessary or proper to effectuate and evidence the release of the security interest in the Patent Collateral.

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IN WITNESS WHEREOF, Collateral Agent has caused this Release to be executed by its duly authorized representative as of the Effective Date.

GOLDMAN SACHS LENDING PARTNERS
LLC, as Collateral Agent

By: 

Name:

Title:

Douglas Tansey
Authorized Signatory

[Signature Page to Release of Security Interest in Patents]

PATENT
REEL: 031751 FRAME: 0832

SCHEDULE A
TO
RELEASE OF SECURITY INTEREST IN PATENTS

PATENTS AND PATENT APPLICATIONS

Patent Title	Application Number Application Date	Patent Number Issue Date
LAMINATES FOR HIGH SPEED AND HIGH FREQUENCY PRINTED CIRCUIT BOARDS	11634471 12/6/2006	---
THERMOPLASTIC FILM, REINFORCED HOLLOW GLASS MICROSPHERE REINFORCED LAMINATES FOR THIN LOW DIELECTRIC CONSTANT SUBSTRATES	07635087 12/28/1990	5098781 3/24/1992
HIGH PERFORMANCE CURABLE PPO/MONOMERIC EPOXY COMPOSITIONS WITH TIN METAL SALT COMPATIBILIZING AGENT	07677229 3/29/1991	5262491 11/16/1993
SYSTEM AND METHOD FOR MANUFACTURING COPPER CLAD GLASS EPOXY LAMINATES	07685337 4/15/1991	5160567 11/3/1992
SYSTEM OF ELECTRONIC LAMINATES WITH IMPROVED REGISTRATION PROPERTIES	07982797 11/30/1992	5350621 9/27/1994
POLYIMIDE RESIN LAMINATES	07993147 12/18/1992	5334696 8/2/1994
MULTIPLE LAYER PRINTED CIRCUIT BOARDS AND METHOD OF MANUFACTURE	08110437 8/23/1993	5362534 11/8/1994
LOW EXPANSION DIELECTRIC COMPOSITIONS	10952102 9/28/2004	---
FLAME RETARDANT COMPOSITIONS	12610004 10/30/2009	---
SUBSTITUTED CYANOGUANIDINES AS CURING AGENTS FOR EPOXY RESINS	08153401 11/16/1993	5387656 2/7/1995
COPPER-CLAD LAMINATE AND PRINTED WIRING BOARD	08143849 10/26/1993	5437914 8/1/1995
PROCESS FOR MEASUREMENT OF THE DEGREE OF CURE AND PERCENT RESIN OF GLASS-FIBER-REINFORCED EPOXY RESIN PREPREG	08239072 5/6/1994	5457319 10/10/1995
SYSTEM OF ELECTRONIC LAMINATES WITH IMPROVED REGISTRATION PROPERTIES	08246054 5/19/1994	5464658 11/7/1995
CURING EPOXY RESINS USING DICY, IMIDAZOLE AND ACID	08340962 11/17/1994	5508328 4/16/1996
COPPER FOIL LAMINATE FOR PROTECTING MULTILAYER ARTICLES	08126478 9/24/1993	5512381 4/30/1996
COPPER-CLAD LAMINATE AND PRINTED WIRING BOARD	08500540 7/11/1995	5545466 8/13/1996
METHOD OF MAKING A CIRCUIT BOARD OR LAYER THEREOF INCLUDING SEMI-CURING A SECOND ADHESIVE COATED ON A CURED FIRST ADHESIVE	08297792 8/30/1994	5557843 9/24/1996

SOLDER MASK FOR MANUFACTURE OF PRINTED CIRCUIT BOARDS	08570260 12/11/1995	5626774 5/6/1997
ROLLER POSITION CONTROLLER FOR A CONTINUOUS BELT PRESS	08562312 11/22/1995	5626804 5/6/1997
CIRCUIT BOARD PREPREG WITH REDUCED DIELECTRIC CONSTANT	08442119 5/16/1995	5670250 9/23/1997
METHOD OF MANUFACTURING LAMINATES AND PRINTED CIRCUIT BOARDS	08422510 4/13/1995	5779870 7/14/1998
METHODS OF MANUFACTURING VOIDLESS RESIN IMPREGNATED WEBS	09224991 1/4/1999	6083855 7/4/2000
POSITIVE ACTING PHOTODIELECTRIC COMPOSITION	09024997 2/17/1998	6168898 1/2/2001
FILLERS FOR IMPROVED EPOXY LAMINATES	08620525 3/22/1996	6187852 2/13/2001
HIGH DENSITY PRINTED CIRCUIT SUBSTRATE AND METHOD OF FABRICATION	09123952 7/28/1998	6242078 6/5/2001
FABRICATION OF HIGH DENSITY MULTILAYER INTERCONNECT PRINTED CIRCUIT BOARDS	09054264 4/3/1998	6255039 7/3/2001
TALC PARTICLES AS FILLERS FOR IMPROVED EPOXY LAMINATES	09735984 12/13/2000	6322885 11/27/2001
CYANATE ESTER BASED THERMOSET COMPOSITIONS	09760125 1/16/2001	6403229 6/11/2002
EPOXY RESINS, STYRENE-MALEIC ANHYDRIDE COPOLYMER AND CO-CROSSLINKING AGENT	09269014 6/14/1999	6509414 1/21/2003
SURFACE ENHANCED METAL PRESS PLATES FOR USE IN MANUFACTURE OF LAMINATES AND MULTILAYER MATERIALS AND METHOD OF MAKING SAME	09666431 9/21/2000	6584820 7/1/2003
METHOD OF BULK FABRICATING PRINTED WIRING BOARD LAMINATES	09671386 9/27/2000	6609294 8/26/2003
PARALLEL PLATE BURIED CAPACITOR	09276370 3/25/1999	6618238 9/9/2003
MANUFACTURE OF PREPREGS AND LAMINATES WITH RELATIVELY LOW DIELECTRIC CONSTANT FOR PRINTED CIRCUIT BOARDS	10035975 11/9/2001	6632511 10/14/2003
COMPENSATION MODEL AND REGISTRATION SIMULATION APPARATUS AND METHOD FOR MANUFACTURING OF PRINTED CIRCUIT BOARDS	09270303 3/15/1999	6658375 12/2/2003
LASER CUTTING OF LAMINATES FOR ELECTRICAL INSULATION TESTING	10316665 12/11/2002	6768316 7/27/2004
PRODUCTION OF LAMINATES FOR PRINTED WIRING BOARDS USING PROTECTIVE CARRIER	10044628 1/10/2002	6955740 10/18/2005
THERMOSETTING RESIN COMPOSITION FOR HIGH PERFORMANCE LAMINATES	10309720 12/4/2002	7090924 8/15/2006
LAMINATE COMPOSITION	10385044 3/10/2003	7255927 8/14/2007

THERMOSETTING RESIN COMPOSITION FOR HIGH PERFORMANCE LAMINATES	11132846 5/19/2005	7425371 9/16/2008
REDUCING DUSTING OF EPOXY LAMINATES	08540429 10/10/1995	7507471 3/24/2009
EPOXY RESIN, SMA COPOLYMER AND BIS-MALEIMIDETRIAZINE RESIN	11185259 7/20/2005	7521494 4/21/2009
FLAME RETARDANT COMPOSITIONS	10952033 9/28/2004	7687556 3/30/2010
PREPREG AND LAMINATE OF EPOXY RESIN, STYRENE-MALEIC ANHYDRIDE COPOLYMER AND BIS-MALEIMIDETRIAZINE	12417463 4/2/2009	7713621 5/11/2010
LAMINATE MADE FROM EPOXY RESIN, STYRENE-MALEIC ANHYDRIDE COPOLYMER AND CROSSLINKERS	12139981 6/16/2008	7897258 3/1/2011
REDUCING DUSTING OF EPOXY LAMINATES	12398762 3/5/2009	7910202 3/22/2011
EPOXY RESIN, STYRENE-MALEIC ANHYDRIDE COPOLYMER AND CROSSLINKING AGENT	11637222 12/11/2006	8022140 9/20/2011
FLAME RETARDANT COMPOSITIONS WITH A PHOSPHORATED COMPOUND	11269132 11/8/2005	8129456 3/6/2012
THERMOSETTING RESIN COMPOSITION FOR HIGH PERFORMANCE LAMINATES	12773480 5/4/2010	8227084 7/24/2012
LAMINATE COMPOSITION FOR PRODUCING REDUCED CURL FLAT THIN CORE LAMINATE	10858344 6/1/2004	8263225 9/11/2012